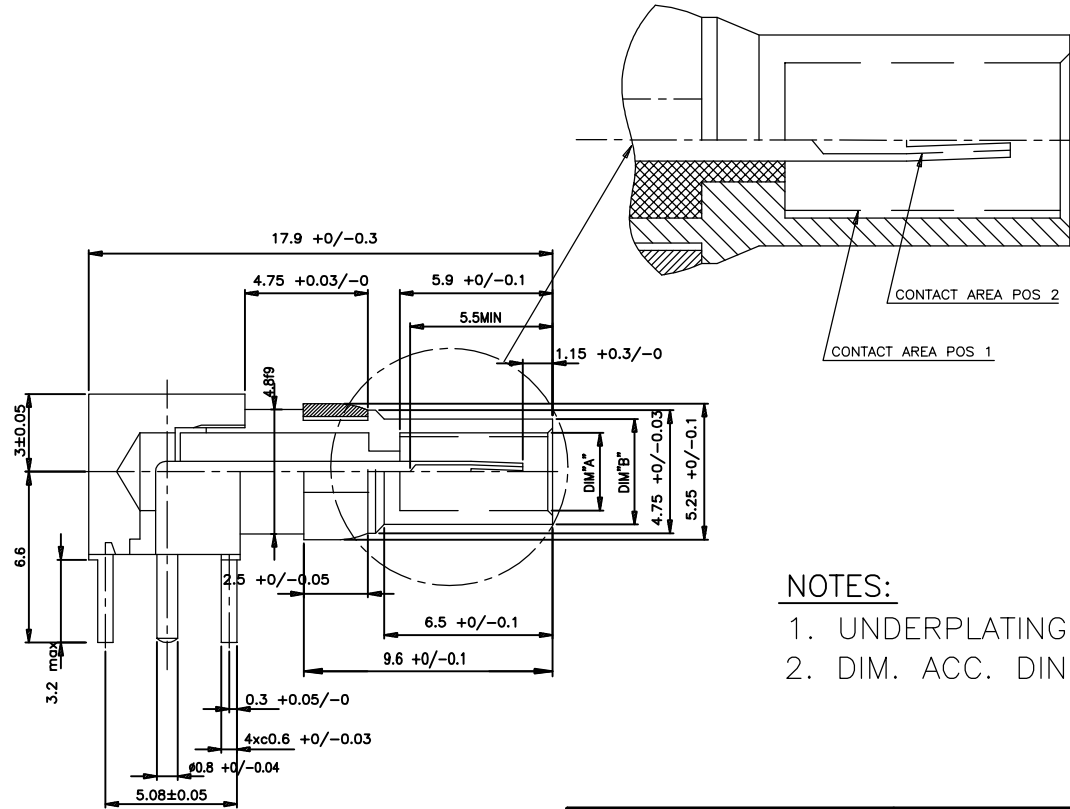


LEAD-FREE P/N	IMPEDANCE	PLATING IN CONTACT AREA		DIM "A"	DIM "B"	
		POS 1	POS 2			
71637-103LF	50 Ohm	1.3 μm Au MIN	1.3 μm Au MIN	3.0/+0.05/-0	4.07/+0/-0.04	
71637-104LF	75 Ohm	1.3 μm Au MIN	1.3 μm Au MIN	3.35/+0.03/-0	4.3/+0.01/-0.03	
71637-104ELF	75 Ohm	1.3 μm Au MIN	1.3 μm Au MIN	3.35/+0.03/-0	4.3/+0.01/-0.03	Order quantity >10000



NOTES:

1. UNDERPLATING Ni.
2. DIM. ACC. DIN 41626

European Views

NOTE:RoHS INFORMATIONS

- The "LF" product meets European union Directives and other country regulations as described in GS-22-008.
- The product is not intended to be exposed to a manufacturing solder process.
- Packaging spec: see GS-14-920.

rev	ecn no	dr	date
G	LS06-0022	LGO	2006/03/06
H	LS07-0214	LGO	2007/08/20
J	LS08-0057	LGO	2008/02/18
K	F11-0306	APA	2011/09/19
L	F12-0030	APA	2012/03/19
-	-	-	-
-	-	-	-

www.fciconnect.com		surface ISO 1302	tolerance std ISO 406 ISO 1101	projection ISO 1101	mm
TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	GOISNARD	2006/03/06	ANGULAR	0.X	± 0.1
Eng	GOISNARD	2006/03/06	LINEAR	0.XX	± 0.1
Chr	LEGARE	2006/03/06	0.XX ± 2	0.XXX	± 0.1
Appr	LEGARE	2006/03/06	Product family	BACKPANEL	Spec ref -
FCJ		title FEMALE COAX INSERT RA STB		dwg no 71637	
-		-		Rev. L	
-		-		CUSTOMER sheet 1 of 1	